

**ECS  
BROKERAGE  
EVENT**

**CELESTIA** | TST

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# CELESTIA at a glance

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## LOCATIONS



**+35M€**

sales

**+200**

employees

**+25%**

research and development

**6**

companies

**5**

countries

# CELESTIA | TST

## ECS R&D Background

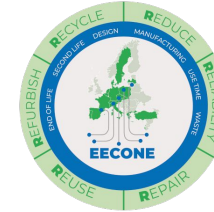
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Distributed Artificial Intelligence Systems



Long Life Power Platforms for IoT

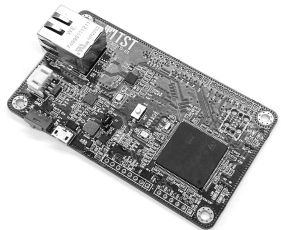


European ECOsystems for green Electronics



**CELESTIA**

**TST**



Smart Edge Devices.  
ML on the edge.  
Digital Industry Supply Chain:  
Energy Management demonstrator.



ML embedded models and algorithms for predictive maintenance and anomaly detection.  
IoT Device: bearing condition monitoring with energy harvesting .



TST leads UC10: Green Soil Probe.  
Tools for estimation of batteries RUL (optimize recycling / replacement).  
Reuse components, improve recyclability, reduce waste, use more sustainable materials.

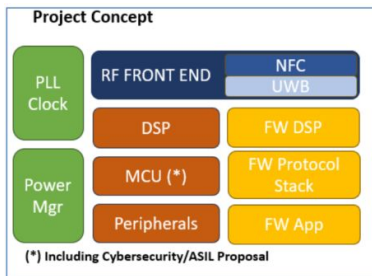
# CELESTIA | TST

## ECS R&D Background

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### RISCCOM

Secure low-power multipurpose system based on RISC-V for wireless communications



Low-power microelectronics  
RISC-V  
UWB technology  
DSP and cybersecurity  
Automotive IoT

### PROACTIF

Unmanned Vehicles for Civil Security and Surveillance Missions



TST leads Mission 2.4: Port Security.  
Critical infrastructure safety and security: autonomous surveillance, perimeter protection, threats detection.  
Mini-UGV platform:  
Modular, upgradeable, all-terrain, indoor-outdoor, collaborative.



## Collaboration Expectations

EU Programmes	Chips JU, Horizon Europe
Scope	Technology development, new market access
Potential research and innovation fields	<ul style="list-style-type: none"> <li>Edge AI and Embedded ML</li> <li>HW-FW codesign</li> <li>AI assisted IoT design and assessment</li> <li>Edge-Cloud Continuum</li> <li>Autonomous Robotics</li> <li>Microelectronics</li> <li>SiGe, GaAs, GaN MMIC design</li> <li>SiP and Chiplets, heterogeneous integration</li> <li>AI assisted design</li> <li>RISC-V</li> </ul>